IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier Informa	ation						·							
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
onsemi											2025-08-01			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			P	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number Mfr Ite		em Number Mfr Item Name			Effectiv		Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
		FFSM0865A 650V		650V 8A SIC SBD			2025-08-01					55.8475	mg	Each
	Process Informati		arminal Paga	Alloy	STD-020 MSL 1	Dating	Dook Proc	ogg Pody T	amparatus	re Max Time at Peak	Tomporatu	ro Numb	er of Reflow Cyc	alas
			Terminal Base Alloy J-ST CU Alloy 1		81D-020 MSL 1	Kaung	260	ess Body 16	SS Body Temperature   Max Time at Peak   C   30		seconds 3		er of Reflow Cyc	cies
•	(Sii) - anneaied	C	U Alloy	1			200		IC	30	second	s [ <b>3</b>		
omments	me of neals townst	o dunina1	domina ia 10-1	10 seconds										
	me at peak temperatur													
: more information	n regarding material c	omposition p	please refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.46	mg	Supplier	Silicon Carbide	409-21-2		8.46	mg
Die Attach Solder	5.135	mg	Supplier	Silver (Ag)	7440-22-4		0.1284	mg
			A	Lead (Pb)	7439-92-1	7a	4.7499	mg
			Supplier	Tin (Sn)	7440-31-5		0.2568	mg
Lead Frame	27.5725		Supplier	Silver (Ag)	7440-22-4		0.0062	mg
			Supplier	Tin (Sn)	7440-31-5		3.7	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0263	mg
			Supplier	Iron (Fe)	7439-89-6		0.54	mg
			Supplier	Copper (Cu)	7440-50-8		23.3	mg
Mold Compound-Black	112.99			Epoxy resin	proprietary data		6.7794	mg
			Supplier	Phenolic Resin	Proprietary Data		6.7794	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5649	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		96.0415	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		2.8247	mg
Wire Bond - Al	1.69	mg	Supplier	Aluminum (Al)	7429-90-5		1.69	mg